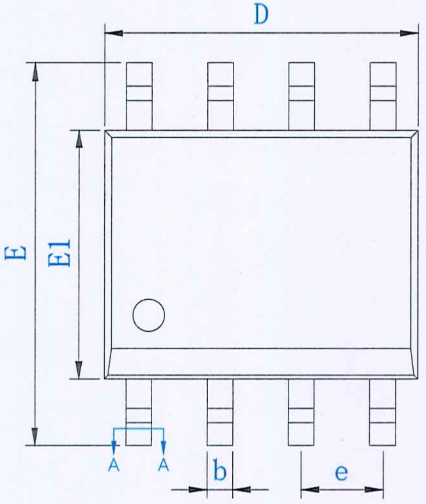
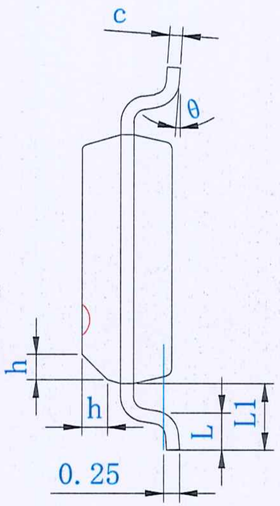
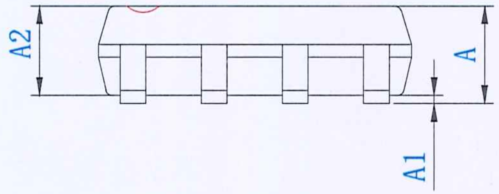
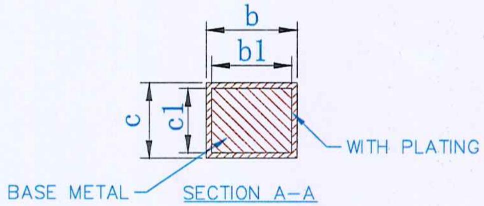




	SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS	A	–	–	1.75
STAND OFF	A1	0.05	–	0.20
MOLD TOTAL THICKNESS	A2	1.30	1.40	1.50
LEAD WIDTH	b	0.37	–	0.47
LEAD WIDTH	b1	0.35	0.40	0.45
LEAD THICKNESS	c	0.20	–	0.24
LEAD THICKNESS	c1	0.19	0.203	0.22
MOLD LENGTH	D	4.80	4.90	5.00
LEAD SPAN	E	5.80	6.00	6.20
MOLD WIDTH	E1	3.80	3.90	4.00
LEAD PITCH	e	1.27 BSC		
LEAD SOLE LENGTH	L	0.40	0.60	0.80
LEAD LENGTH	L1	1.05 BSC		
LEAD FORM ANGLE	θ	0°	–	8°





REV	DESCRIPTION OF CHANGE	DRAWER	ISSUE DATE
N	REFER TO JEDEC'S STANDARD(REF JEDEC MS-012)	CAIZEXIAN	2023/04/26
M	UPDATE DRAWING	DOU	2022/05/23
L	INITIAL ISSUE	DRAWER	ISSUEDATE

TITLE SOP8 POD

DWG No. C-OL-007

MATERIAL

CPC 气派科技 chippacking

X	REV	N	SHEET	1/1	DWN	CaiZexian	2023/04/26
X.X			SCALE	1:1	CKD		2023.4.26
X.XX X.XXX			UNIT	MM	APPD		2023-4-26